Result of tenders of RMB Sovereign Bonds held on June 14, 2023

The following is issued on behalf of the Hong Kong Monetary Authority:

Result of tenders of RMB Sovereign Bonds held on June 14, 2023:

Tender Result
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Tender Date : June 14, 2023
Bonds available for Tender : 2-year RMB Bonds
Issue Number : BCMKFB23013
Issue and Settlement Date : June 16, 2023
Maturity Date : June 16, 2025 (or the closest coupon payment date)
Application Amount : RMB 21,739 million
Issue Amount : RMB 6,000 million
Average accepted Coupon Rate : 2.16 per cent
Highest accepted Coupon Rate (Bonds' Coupon) : 2.20 per cent
Lowest accepted Coupon Rate : 1.60 per cent
Allocation Ratio : Approximately 96.29 per cent

Tender Result
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Tender Date : June 14, 2023
Bonds available for Tender : 3-year RMB Bonds
Issue Number : BCMKFB23014
Issue and Settlement Date : June 16, 2023
Maturity Date : June 16, 2026 (or the closest coupon payment date)
Application Amount : RMB 18,062 million
Issue Amount : RMB 4,000 million
Average accepted Coupon Rate : 2.22 per cent
Highest accepted Coupon Rate (Bonds' Coupon) : 2.30 per cent
Lowest accepted Coupon Rate : 1.60 per cent
Allocation Ratio : Approximately 68.43 per cent

Tender Result

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Tender Date : June 14, 2023

Bonds available for Tender : 10-year RMB Bonds

Issue Number : BCMKFB23015

Issue and Settlement Date : June 16, 2023

Maturity Date : June 16, 2033 (or the closest coupon payment date)

Application Amount : RMB 10,224 million

Issue Amount : RMB 2,000 million

Average accepted Coupon Rate : 2.65 per cent

Highest accepted Coupon Rate (Bonds' Coupon) : 2.71 per cent

Lowest accepted Coupon Rate : 2.30 per cent

Allocation Ratio : Approximately 37.78 per cent